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Abstract of JP5302199

PURPOSE: To control the composition of a copper plating bath by equalizing the electrolytic current in a copper ion replenishing tank to that in a plating bath. CONSTITUTION: Copper ion and hydroxide ion are supplied from a copper ion replenishing tank 1 to a copper plating bath 2 in copper plating using an insoluble electrode. The tank 1 is separated by a thin membrane impermeable to copper ion and permselective to hydroxide ion. One compartment of the tank 1 is filled with a copper plating soln., a copper metallic electrode 7 is dipped in the compartment, and electrolysis is carried out between the positive electrode 7 and a negative counter electrode to generate copper ion from the electrode 7. In this case, the electrolytic current in the tank 1 is equalized to that in the plating bath. Consequently, the composition of the copper plating bath is controlled by replenishing a plating bath contg. copper ion.



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